TAIYO PSR-4000MP

LIQUID PHOTOIMAGEABLE SOLDER MASK

- Screen or Spray Application
- Dark Green, Matte Finish
- Excellent Solder Ball Resistance
- Resistance to No-Clean Flux Residue
- Wide Processing Window
- Fine Dam Resolution
- Withstands ENIG & Immersion Tin
- Hard Surface Finish
- Low Odor



PROCESSING PARAMETERS FOR PSR-4000MP

PSR-4000MP is a two-component, matte dark Green, alkaline developable LPI solder mask product for flood screen and spray application methods. This product has a very low odor, a wide process window and is capable of withstanding alternate metal finishes such as ENIG and immersion Tin. It has a matte Dark Green finish and provides excellent solder ball resistance in no clean flux assembly applications. **PSR-4000MP** meets or exceeds the requirements of IPC SM-840C Class H and Class T, Bellcore GR-78-CORE Issue 1, and has a UL flammability rating of 94V-0.

PSR-4000MP COMPONENTS

PSR-4000MP / CA-40MP

Mixing Ratio 100 parts 25 parts Color Green White

Mixed Properties

Solids 80% Viscosity 140 – 180 ps Specific Gravity 1.58

MIXING

PSR-4000MP is supplied in pre-measured containers with a mix ratio by weight of 100 parts **PSR-4000MP** and 25 parts **CA-40MP**. **PSR-4000MP** can be mixed by hand with a mixing spatula for 10 – 15 minutes. Mixing can be done with a mechanical mixer at low speeds to minimize shear thinning for 10 – 15 minutes. Also, mixing can be done with a paint shaker for 10 – 15 minutes.

PRE-CLEANING

Prior to solder mask application, the printed circuit board surface needs to be cleaned. Various cleaning methods include Pumice, Aluminum Oxide, Mechanical Brush, and Chemical Clean. All of these methods will provide a clean surface for the application of **PSR-4000MP**. Hold time after cleaning the printed circuit board should be held to a minimum to reduce the oxidation of the copper surfaces.



PROCESSING PARAMETERS FOR PSR-4000MP

SCREEN PRINTING

Method: Single Sided and Double Sided Screening

Screen Mesh: 86 – 110

Screen Mesh Angle: 22.5° BiasScreen Tension: 20 - 28 Newtons

Squeegee: 60 – 80 durometer
Squeegee Angle: 27 – 35°

• Printing Mode: Flood / Print / Print

• Flood Pressure: 20 – 30 psi

• Printing Speed: 2.0 – 9.9 inches/sec

• Printing Pressure: 60 – 100 psi

TACK DRY CYCLE

The Tack Dry step is required to remove solvent from the solder mask film and produce a firm dry surface. The optimum dwell time and oven temperature will depend on oven type, oven loading, air circulation, exhaust rate, and ramp times. Excessive tack dry times and temperature will result in difficulty developing solder mask from through holes and a reduction in photo speed. Insufficient tack dry will result in artwork marking and/or sticking. Typical tack dry conditions for **PSR-4000MP** are as followed:

Oven Temperature: 150 - 185°F (65 - 85°C)

For Single-Sided (Batch Oven)

1st Side: Dwell Time: 10 - 20 minutes 2nd Side: Dwell Time: 25 - 45 minutes

For Double-Sided (Conveyorized or Batch Oven)

Dwell Time: 25 - 60 minutes

EXPOSURE

PSR-4000MP requires UV exposure to define solder mask dams and features. The spectral sensitivity of **PSR-4000MP** is in the area of 365 nm. Exposure times will vary by bulb type and age of the bulb. Below are guidelines for exposing **PSR-4000MP**.

- Exposure Unit: 5 kW or higher
- Stouffer Step 21: Clear 8 minimum (on metal / under phototool)
- Energy: 250 mJ / cm² minimum (under phototool)



PROCESSING PARAMETERS FOR PSR-4000MP

DEVELOPMENT

PSR-4000MP is developed in an aqueous sodium or potassium carbonate solution. Developing can be done in either a horizontal or vertical machine.

- Solution: 1% by wt. Sodium Carbonate or 1.2% Potassium Carbonate
- pH: 10.6 or greater
- Temperature: 85 105°F (29 41°C)
- Spray Pressure: 25 45 psi
- Dwell Time in developing chamber: 45 90 seconds
- Water rinse is needed to remove developer solution followed by drying of the board

FINAL CURE PSR-4000MP needs to be thermally cured to insure optimal final property performance. Thermal curing can be done in a batch oven or conveyorized oven.

- Temperature: 275 300°F (135 149°C)
- Time: 45 60 minutes

UV CURE (OPTIONAL) PSR-4000MP has good solder ball resistance. For even better solder ball resistance a UV Bump can be done after Final Cure.

- UV Energy: 2000 3000 mJ / cm²
- Lamps: High Pressure Mercury Lamps

For Process Optimization please contact your local Taiyo America Representative

FINAL PROPERTIES FOR PSR-4000MP

IPC-SM-840C, Class H & T, Solder Mask Vendor Testing Requirements

	SM-840		
TEST	PARAGRAPH	REQUIREMENT	RESULT
Visual	3.4.8	Uniform in Appearance	Pass
Curing	3.4.5	Ref: 3.6.1.1, 3.7.1 and 3.7.2	Pass
Non-Nutrient	3.4.6	Does not contribute to biological growth	Pass
Dimensional	3.4.10	No Solder Pickup and Withstand 500 VDC	Pass
Pencil Hardness	3.5.1	Minimum "F"	Pass – 7H
Adhesion	3.5.2	Rigid – Cu, Ni, FR-4	Pass
Machinability	3.5.3	No Cracking or Tearing	Pass
Resistance to Solvents			
and Cleaning Agents	3.6.1.1	Table 3 Solvents	Pass
Hydrolytic Stability and Aging	3.6.2	No Change after 28 days of 95-99°C and 90-98% RH	Pass
Solderability	3.7.1	No Adverse Effect J-STD-003	Pass
Resistance to Solder	3.7.2	No Solder Sticking	Pass
Dielectric Strength	3.8.1	500 VDC / mil Minimum	2900 VDC/mil
Thermal Shock	3.9.3	No Blistering, Crazing or De-lamination	Pass

Specific Class "H" Requirements

	SM-840		
TEST	PARAGRAPH	REQUIREMENT	RESULT
Flammability	3.6.3	UL 94V-0	Pass – File #E166421
Insulation Resistance	3.8.2		
Before Soldering		5 x 10 ⁸ ohms minimum	Pass (3.7 x 10 ¹² ohms) Pass (3.1 x 10 ¹³ ohms)
After Soldering		5 x 10 ⁸ ohms minimum	Pass (3.1 x 10 ¹³ ohms)
Moisture & Insulation Resistance	3.9.1		
Before Soldering-In Chamber		5 x 10 ⁸ ohms minimum	Pass (6.4 x 10 ⁹ ohms)
Before Soldering-Out of Chamber		5 x 10 ⁸ ohms minimum	Pass (1.2 x 10 ¹³ ohms)
After Soldering-In Chamber		5 x 10 ⁸ ohms minimum	Pass (1.2 x 10 ¹³ ohms) Pass (1.0 x 10 ¹⁰ ohms)
After Soldering-Out of Chamber		5 x 10 ⁸ ohms minimum	Pass (1.0 x 10 ¹³ ohms)
Electrochemical Migration	3.9.2	>2.0 x 10 ⁶ ohms, no	Pass (1.25 x 10 ¹² ohms)
_		dendritic growth	

Specific Class "T" Requirements

	SM-840		
TEST	PARAGRAPH	REQUIREMENT	RESULT
Flammability	3.6.3	Bellcore 0 ₂ Index – 28 minimum	Pass – 75
Insulation Resistance	3.8.2	_	
Before Soldering		5 x 10 ⁸ ohms minimum	Pass (4.3 x 10 ¹³ ohms)
After Soldering		5 x 10 ⁸ ohms minimum	Pass (1.7 x 10 ¹² ohms)





FINAL PROPERTIES FOR PSR-4000MP

Specific Class "T" Requirements

TEST	SM-840 PARAGRAPH	REQUIREMENT	RESULT
Moisture & Insulation Resistance	3.9.1		
Before Soldering-In Chamber		5 x 10 ⁸ ohms minimum	Pass (9.9 x 10 ⁹ ohms)
Before Soldering-Out of Chamber		5 x 10 ⁸ ohms minimum	Pass (4.2 x 10 ¹¹ ohms)
After Soldering-In Chamber		5 x 10 ⁸ ohms minimum	Pass (1.9 x 10 ⁹ ohms)
After Soldering-Out of Chamber		5 x 10 ⁸ ohms minimum	Pass (2.2 x 10 ¹¹ ohms)
Electrochemical Migration	3.9.2	< 1 decade drop, no dendritic	Pass
		growth	

Additional Tests / Results

TEST		REQUIREMENT	RESULT
Dielectric Constant		Internal Test at 1 MHz	4.7
Dissipation Factor		Internal Test at 1 MHz	0.0220
Electroless Nickel / Immersion Gold Resistance		Nickel (85C/30 min) Tape Test Adhesion	Pass
Solvent Resistance	Acetone:	No attack – 24 hours	Pass
	MEK:	No attack – 24 hours	Pass
	IPA:	No attack – 24 hours	Pass
	PMA:	No attack – 24 hours	Pass
Acid Resistance	HCI – 10%:	No attack – 30 Minutes	Pass
	$H_2SO_4 - 10\%$:	No attack – 30 Minutes	Pass
Base Resistance	NaOH – 10%:	No attack – 30 Minutes	Pass
Bo	oiling Water Resistance:	No attack – 15 Minutes	Pass
Solder / Flux Resistance (Alph	nametals)		
A	Alpha 857 water soluble:	No attack – 1 x 10 sec float (260C)	Pass
	NR060 no-clean:	No attack – 1 x 10 sec float (260C)	Pass
	3355-NB rosin-based:	No attack – 1 x 10 sec float (260C)	Pass
	NR-3000A4 no-clean:	No attack – 1 x 10 sec float (260C)	Pass
Solder / Flux Resistance (Multicore)		No attack – 1 x 10 sec float (260C)	Pass
	X32-10M no-clean:		
	X32-06l no-clean:	No attack – 1 x 10 sec float (260C)	Pass
Solder/Flux Resistance-(Sanwa)SR-270 rosin-based:		No attack – 1 x 10 sec float (260C)	Pass
Conformal Coating Adhesion: Humiseal 1 B31 acrylic:		Crosscut (10/10) after tape	100/100
Humiseal 1A20 urethane:		Crosscut (10/10) after tape	100/100
Dow 0	Corning 3-1753 silicone:	Crosscut (10/10) after tape	100/100
Glue Dot Adhesion – Loctite 3	609	Adhesion of Glue Dot to PSR-4000MP	Excellent

Taiyo America, Inc. (TAIYO) warrants its products to be free from defects in materials and workmanship for the specified warranty period (PSR-400MP/ CA-40MP Warranty period is 9 Months) provided the customer has, at all times, stored the ink at a temperature of 68°F or less. TAIYO accepts no responsibility or liability for damages, whether direct, indirect, or consequential, resulting from failure in the performance of its products. If a TAIYO product is found to be defective in material or workmanship, its liability is limited to the purchase price of the product found to be defective. TAIYO MAKES NO OTHER WARRANTY, EXPRESS OR IMPLIED, AND MAKES NO WARRANTY OF MERCHANTABILITY OR OF FITNESS FOR ANY PARTICULAR PURPOSE. TAIYO'S obligation under this warranty shall not include any transportation charges or costs of installation or any liability for direct, indirect, or consequential damages or delay. If requested by TAIYO, products for which a warranty claim is made are to be returned transportation prepaid to TAIYO'S factory. Any improper use or any alteration of TAIYO'S product by the customer, as in TAIYO'S judgment affects the product materially and adversely, shall void this limited warranty.

